Breakover diodes

BR211 series

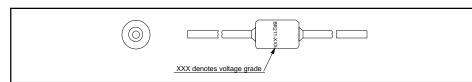
GENERAL DESCRIPTION

QUICK REFERENCE DATA

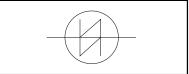
A range of bidirectional, breakover diodes in an axial, hermetically sealed, glass envelope. These devices feature controlled breakover voltage and high holding current together with high peak current handling capability. Typical applications include transient overvoltage protection in telecommunications equipment.

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _(BO) I _H I _{TSM}	BR211-100 to 280 Breakover voltage Holding current Non-repetitive peak current	100 150 -	280 - 40	V mA A

OUTLINE - SOD84







LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_D	Continuous voltage		-	75% of	V
I _{TSM1}	Non repetitive peak current	10/320 μs impulse equivalent to 10/700 μs, 1.6 kV voltage impulse (CCITT K17)	-	V _{(BO)typ} 40	А
I _{TSM2}	Non repetitive on-state current	half sine wave; t = 10 ms;	-	15	A
l²t dl _⊤ /dt	I ² t for fusing Rate of rise of on-state current after V _(BO) turn-on	$T_j = 70$ °C prior to surge $t_p = 10$ ms $t_p = 10 \mu s$	- -	1.1 50	A²s A/μs
P _{tot}	Continuous dissipation	$T_a = 25^{\circ}C$ $t_p = 1 \text{ ms; } T_a = 25^{\circ}C$	-	1.2	W
P _{TM} T _{sta}	Peak dissipation Storage temperature	$ t_p = 1 \text{ ms}; \ I_a = 25 \text{ C}$	- -65	50 150	,C
T _a T _{vj}	Operating ambient temperature Overload junction temperature	off-state on-state	-	70 150	ο̈́ς

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-e}	Thermal resistance junction to envelope		-	22	-	K/W
R _{th j-a}	Thermal resistance junction to ambient	mounted as fig:12	-	105		K/W
Z _{th j-a}	Thermal impedance junction to ambient	$t_p = 1 \text{ ms}$	-	2.62	-	K/W
R _{th e-tp}	Thermal resistance envelope to	lead length = 5 mm	-	15	-	K/W
0	tie point	lead length = 10 mm	-	30	-	K/W
R _{th e-a}	Thermal resistance envelope to	lead length = 5 mm	-	440	-	K/W
	ambient	lead length = 10 mm	-	350	-	K/W
R _{th tp-a}	Thermal resistance tie point to	mounted as fig:12	-	70	-	K/W
	ambient	mounted with 1 cm ² copper laminate per lead.	-	55	-	K/W
		mounted with 2.25 cm2 copper laminate per lead	-	45	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{TM} ¹	On-state voltage	I _{TM} = 2 A	-	-	2.5	V
$V_{(BR)}$	Avalanche voltage (min)	$I_{(BR)} = 10_{mA}$				
$V_{(BO)}$	Breakover voltage (max)	$ 1 \le I_S, t_p = 100 \mu S$				
		BR211-100	88	100	112	V
		BR211-120	105	120	135	V
		BR211-140	123	140	157	V
		BR211-160	140	160	180	V
		BR211-180	158	180	202	V
		BR211-200	176	200	224	V
		BR211-220	193	220	247	V
		BR211-240	211	240	269	V
		BR211-260	228	260	292	V
		BR211-280	246	280	314	V
S _(br)	Temperature coefficient of V _(BR)		-	+0.1	-	%/K
$S_{(br)}$	Holding current	$T_i = 25^{\circ}C$	150	-	-	mΑ
	_	$T_i = 70^{\circ}C$	100	-	-	mΑ
$I_{\rm S}^{3}$	Switching current	t _p '= 100 μs	10	200	1000	mΑ
I _S ³	Off-state current	$ V_D = 85\% V_{(BR)min}, T_j = 70^{\circ}C$	-	-	10	μΑ

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¹ Measured under pulsed conditions to avoid excessive dissipation

² The minimum current at which the diode will remain in the on-state

³ The avalanche current required to switch the diode to the on-state

⁴ Measured at maximum recommended continuous voltage. Illuminance \leq 500 lux (daylight); relative humidity < 65%.

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Linear rate of rise of off-state voltage that will not trigger any device	$V_{(DM)} = 85\% \ V_{(BR)min}; \ T_j = 70 \ ^{\circ}C$	1	1	2000	V/μs
C _j		$V_D = 0 \text{ V}$; f = 1 kHz to 1 MHz	-	-	100	pF

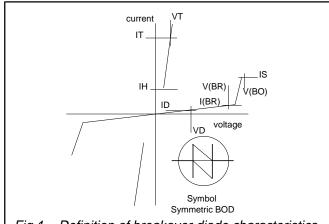


Fig.1. Definition of breakover diode characteristics.

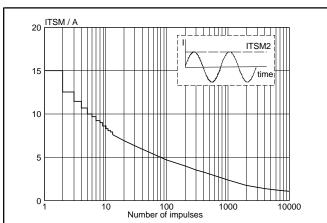


Fig.3. Maximum permissible non-repetitive on-state current based on sinusoidal currents; f = 50 Hz; device triggered at the start of each pulse; $T_j = 70^{\circ}\text{C}$ prior to surge.

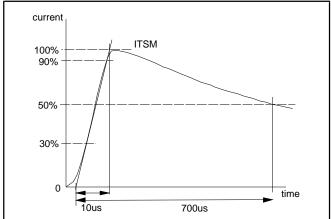


Fig.2. Test waveform for high voltage impulse (I_{TSM1}) according to CCITT vol IX-Rec K17.

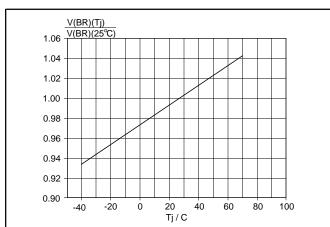


Fig.4. Normalised avalanche breakdown voltage $V_{\rm (BR)}$ and $V_{\rm (BO)}$ as a function of temperature.

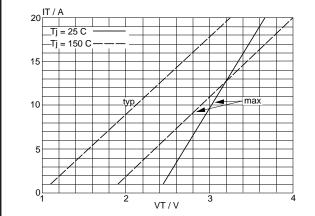


Fig.5. On-state current as a function of on-state voltage; $t_p = 200 \,\mu s$ to avoid excessive dissipation.

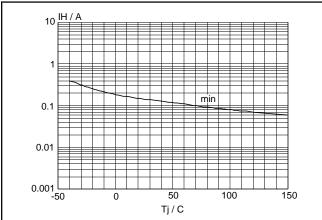


Fig.8. Minimum holding current as a function of temperature.

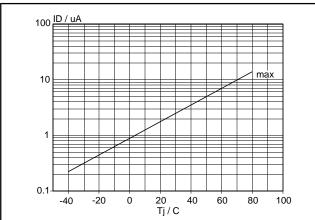


Fig.6. Maximum off-state current as a function of temperature.

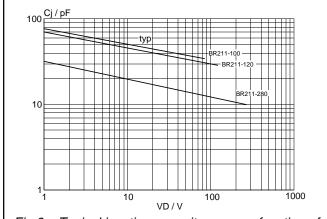


Fig.9. Typical junction capacitance as a function of off-state voltage, f = 1 MHz; $T_i = 25$ °C.

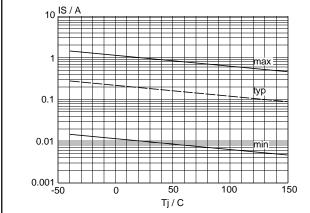


Fig.7. Switching current as a function of junction temperature.

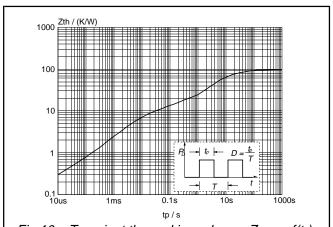
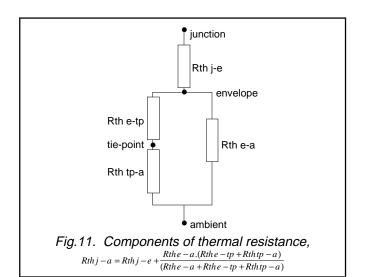
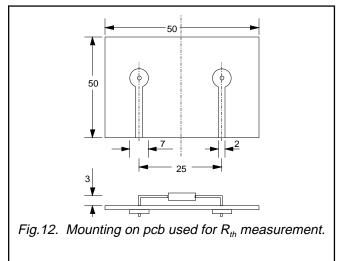


Fig. 10. Transient thermal impedance. $Z_{th j-a} = f(t_p)$.

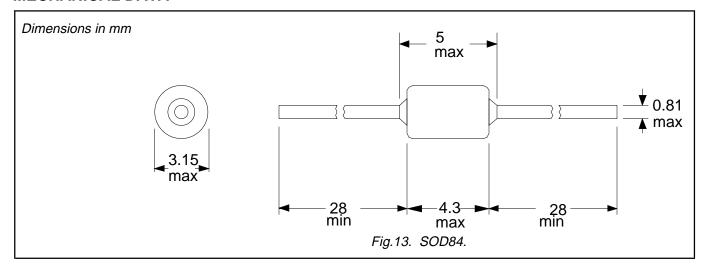
Philips Semiconductors Product specification

Breakover diodes BR211 series





MECHANICAL DATA



DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification This data sheet contains final product specifications.				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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